

Title (en)

REDUCING ELECTROLESS SILVER PLATING SOLUTION AND REDUCING ELECTROLESS SILVER PLATING METHOD

Title (de)

LÖSUNG ZUR STROMLOSEN REDUZIERUNG EINER SILBERPLATTIERUNG UND VERFAHREN ZUR STROMLOSEN REDUZIERUNG EINER SILBERPLATTIERUNG

Title (fr)

SOLUTION DE DÉPÔT D'ARGENT AUTOCATALYTIQUE PAR RÉDUCTION ET PROCÉDÉ DE DÉPÔT D'ARGENT AUTOCATALYTIQUE PAR RÉDUCTION

Publication

EP 2772566 A4 20150701 (EN)

Application

EP 12843616 A 20121009

Priority

- JP 2011235559 A 20111027
- JP 2012076141 W 20121009

Abstract (en)

[origin: EP2772566A1] Provided are a reducing electroless silver plating solution and a reducing electroless silver plating method using the silver plating solution, the reducing electroless silver plating solution being capable of preventing decomposition of silver in the plating solution thereby to maintain stability of the solution and also being capable of preventing excessive roughening of an underlying metal or the like thereby to form a plating film having good film characteristics and a good appearance. The reducing electroless silver plating solution according to the present invention comprises a water-soluble silver salt and a reducing agent, wherein cyanide ions in a concentration of 0.006×10^{-3} mol/L to 12.5×10^{-3} mol/L are contained.

IPC 8 full level

C23C 18/44 (2006.01); **C23C 18/18** (2006.01); **C23C 18/30** (2006.01)

CPC (source: EP US)

C23C 18/1633 (2013.01 - US); **C23C 18/44** (2013.01 - EP US); **C23C 18/1879** (2013.01 - EP US); **C23C 18/30** (2013.01 - EP US)

Citation (search report)

- [XY] GB 1058915 A 19670215 - PHOTOCIRCUITS CORP
- [Y] DE 3419755 A1 19851128 - BAYER AG [DE]
- See references of WO 2013061773A1

Cited by

WO2016102473A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

EP 2772566 A1 20140903; **EP 2772566 A4 20150701**; **EP 2772566 B1 20190306**; JP 2013091833 A 20130516; JP 5840454 B2 20160106; TW 201331413 A 20130801; TW I572742 B 20170301; US 2014242288 A1 20140828; WO 2013061773 A1 20130502

DOCDB simple family (application)

EP 12843616 A 20121009; JP 2011235559 A 20111027; JP 2012076141 W 20121009; TW 101138421 A 20121018; US 201214352145 A 20121009